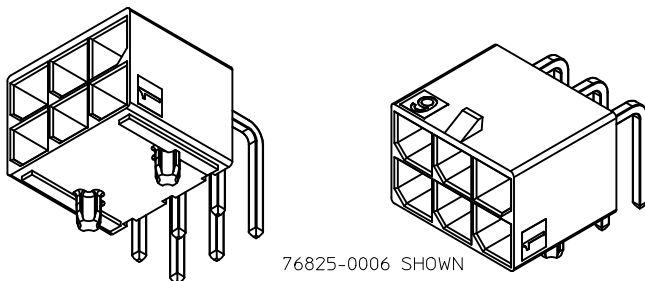
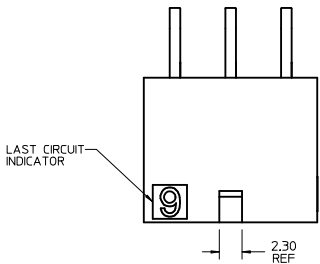
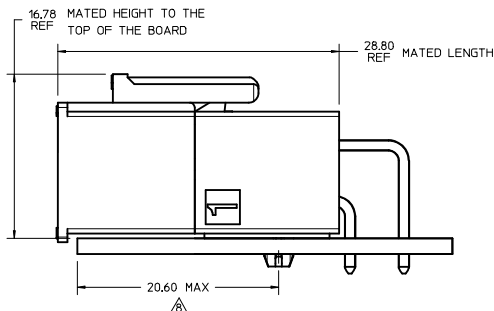
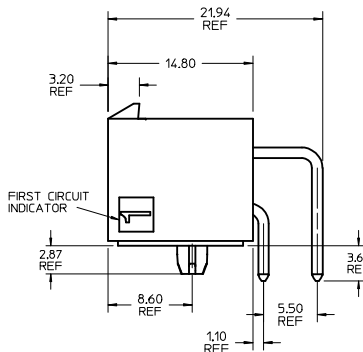
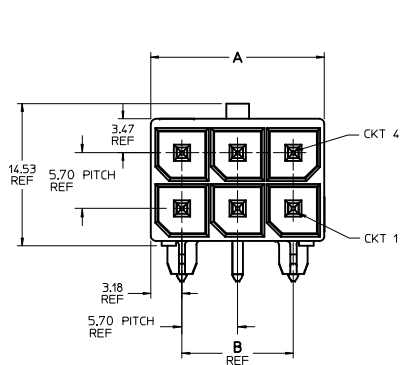


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20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1



76825-0006 SHOWN



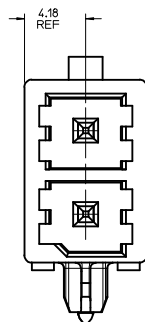
CKT SIZE	PART NO.	PLATING	DIM A	DIM B	DIM C
2	x 76825-0002	TIN	8.35	N/A	9.35
4	x 76825-0004	TIN	12.05	N/A	13.05
6	x 76825-0006	TIN	17.75	11.40	18.75
8	x 76825-0008	TIN	23.45	17.10	24.45
10	x 76825-0010	TIN	29.15	22.80	30.15
12	x 76825-0012	TIN	34.85	28.50	35.45
2	172064-0002	15 GOLD	8.35	N/A	9.35
4	172064-0004	15 GOLD	12.05	N/A	13.05
6	172064-0006	15 GOLD	17.75	11.40	18.75
8	172064-0008	15 GOLD	23.45	17.10	24.45
10	172064-0010	15 GOLD	29.15	22.80	30.15
12	172064-0012	15 GOLD	34.85	28.50	35.45
2	172064-1002	30 GOLD	8.35	N/A	9.35
4	172064-1004	30 GOLD	12.05	N/A	13.05
6	172064-1006	30 GOLD	17.75	11.40	18.75
8	172064-1008	30 GOLD	23.45	17.10	24.45
10	172064-1010	30 GOLD	29.15	22.80	30.15
12	172064-1012	30 GOLD	34.85	28.50	35.45

X = NOT RELEASED

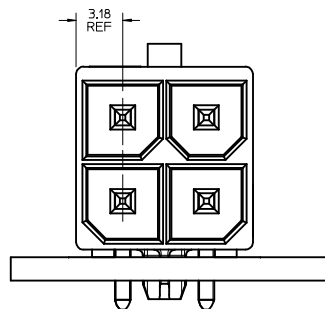
- NOTES:
1. MATERIAL:
HOUSING LCP, UL94V-0, BLACK.
TERMINAL: HIGH CONDUCTIVITY COPPER.
2. TERMINAL PLATING:
(TIN) 1.52 MICROMETER MIN (60 MICROINCH MIN) REFLOWED MATTE TIN OVER
1.27 MICROMETER MIN (50 MICROINCH MIN) MIN NICKEL OVERALL.
(15 GOLD) 0.38 MICROMETER MIN (15 MICROINCH MIN) SELECTIVE GOLD ON CONTACT AREA
WITH 2.54 MICROMETER MIN (100 MICROINCHES MIN) SELECTIVE TIN ON SOLDER AREA
BOTH OVER 1.27 MICROMETER MIN (50 MICROINCHES MIN) NICKEL OVERALL.
(30 GOLD) 0.76 MICROMETER MIN (30 MICROINCH MIN) SELECTIVE GOLD ON CONTACT AREA
WITH 2.54 MICROMETER MIN (100 MICROINCHES MIN) SELECTIVE TIN ON SOLDER AREA
BOTH OVER 1.27 MICROMETER MIN (50 MICROINCHES MIN) NICKEL OVERALL.
3. PRODUCT SPECIFICATION PS-76823-100.
4. PACKAGING: TRAY PACKED PER MOLEX SPECIFICATION PK-76825-0000.
5. PART MATES WITH MOLEX PART NUMBER 170001 AND 171692 SERIES.
6. APPLICATION SPECIFICATION: AS-76823-100
7. PARTS CONFORM TO CLASS 'B' REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.
- ⚠️ TO AVOID INTERFERENCE BETWEEN RECEPTACLE AND PCB, HEADER MUST BE PLACED WITHIN 20.6 MAX FROM EDGE OF PCB AS SHOWN.

ADD NOTE 8 EC NO: UCP2014-5278 DRAWN: DFOX 2014/06/17 CHKD: JELL 2014/06/17 APPROV: SMITH 2014/06/23 REV D5	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		▽=0 ▽=0 ▽=0		mm	INCH	DRAWN BY MKARADI MAS	DATE 2010/11/15	TITLE MEGA-FIT R/A HEADER ASSY 2-12 CKT molex	
			4 PLACES	±---	±---	CHECKED BY	DATE		
			3 PLACES	±---	±---	APPROVED BY	DATE		
	2 PLACES	±0.25	±---	APATEL	2012/06/13				
		1 PLACE	±---	±---	MATERIAL NO.		DOCUMENT NO.	SD-76825-0100	SHEET NO. 1 OF 2
		0 PLACE	±	±	SEE CHART				
	ANGULAR ±1/2°								
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE D		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

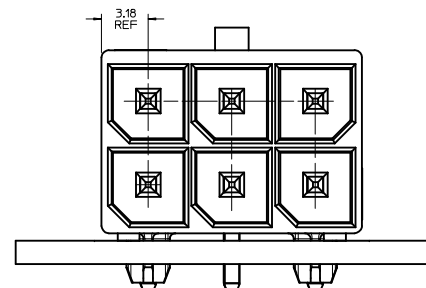
19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1



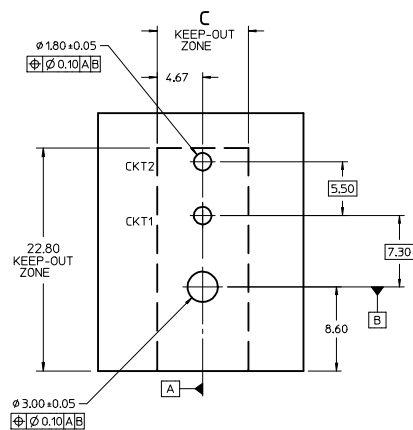
2 CIRCUIT



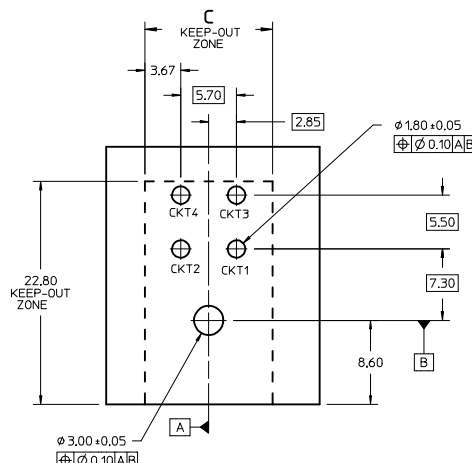
4 CIRCUIT



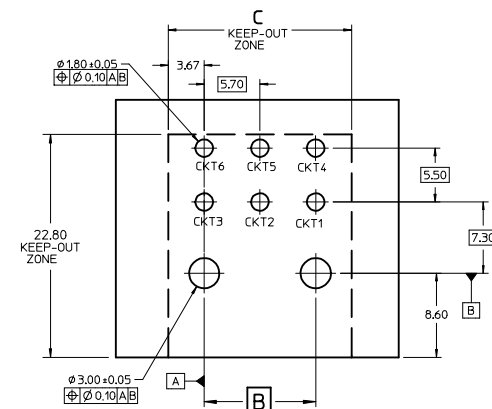
6-12 CIRCUIT



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 1.58 MM/.062 IN
TO 2.36 MM/.093 IN



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 1.58 MM/.062 IN
TO 2.36 MM/.093 IN



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 1.58 MM/.062 IN
TO 2.36 MM/.093 IN

SEE SHT 1 EC NO: UCP2014-5278 DRAWN: JFOX CHKD: JELL APPR: FSMITH REV D5	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- 0 PLACE ± ± ± --- ANGULAR ± 1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY DRAWN BY DATE MKARADIMAS 2010/11/15 CHECKED BY DATE APPROVED BY DATE APATEL 2012/06/13 MATERIAL NO. SEE CHART SIZE D	SCALE 4:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE MEGA-FIT R/A HEADER ASSY 2-12 CKT molex DOCUMENT NO. SD-76825-0100	SHEET NO. 2 OF 2